Fan-out Wafer Level Packaging Cost Analysis

SavanSys cost modeling experts have put together a report on the current state of fan-out wafer level packaging costs. This report presents the most common process flows and evaluates each process segment. A detailed cost analysis is provided for each segment, utilizing sensitivity charts that highlight the cost impact of key variables such as material price, equipment price and throughput.

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Each Process Segment Analysis Includes:
- Direct Cost per Wafer
- Cost Structure
- Cost Drivers
- Sensitivity Analysis of Key Variables
- Process Variations
  ..and more

See back of flier for examples!

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plus PowerPoint Slides

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SavanSys Solutions LLC has been in the cost modeling business for 20 years. SavanSys’ activity based cost modeling approach is used throughout the supply chain by semiconductor giants, fabless companies, and equipment, material, and technology suppliers.

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